

Title (en)

WAFER BOAT AND PLASMA TREATMENT DEVICE FOR WAFERS

Title (de)

WAFERBOOT UND PLASMA-BEHANDLUNGSVORRICHTUNG FÜR WAFER

Title (fr)

PORTE-PLAQUETTES ET DISPOSITIF DE TRAITEMENT PAR PLASMA DE PLAQUETTES

Publication

EP 3378093 A1 20180926 (DE)

Application

EP 16797907 A 20161117

Priority

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Abstract (en)

[origin: WO2017085178A1] The invention relates to a plate element for a wafer boat for the plasma treatment of disk-shaped wafers, in particular semiconductor wafers for semiconductor or photovoltaic applications. The plate element is electrically conductive and has at least one holding unit on each side, for holding a wafer in a wafer holding region. The plate element has at least one recess in at least one side of the plate element and/or at least one opening in the plate element, wherein the at least one recess and/or the at least one opening in the plate element lies at least partially radially outside of the wafer holding region and directly adjacent thereto. The invention further relates to a wafer boat that has a plurality of plate elements of the above type arranged parallel to each other, wherein plate elements arranged adjacent are electrically insulated from each other. The invention further relates to a wafer boat in combination with a plasma treatment device, which has a process chamber for accommodating the wafer boat, means for controlling a process gas atmosphere in the process chamber in an open-loop or closed-loop manner, and at least one voltage source, which can be connected to the electrically conductive plate elements of the wafer boat in a suitable manner in order to apply a voltage between directly adjacent wafers held in the wafer boat.

IPC 8 full level

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Citation (search report)

See references of WO 2017085178A1

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